L Number	Hits	Search Text	DB	Time stamp
1	17	6727594, 6746896, "6180696"	USPAT	2004/07/06 16:20
2	20	6727594, 6746896, "6180696"	USPAT; US-PGPUB	2004/07/06 16:21
3	10	"716945"	USPAT; US-PGPUB	2004/07/06 16:21
4	0	"10716945"	USPAT; US-PGPUB	2004/07/06 16:21
5	0	"716945"	US-PGPUB	2004/07/06 16:23
6	222	heat$3 same die same nozzle	US-PGPUB	2004/07/06 16:43
7	80	(heat$3 same die same nozzle) and substrate	US-PGPUB	2004/07/06 16:44
8	9073	heat$3 same die	US-PGPUB	2004/07/06 16:29
9	4089	(heat$3 same die) and substrate	US-PGPUB	2004/07/06 16:42
10	1033	((heat$3 same die) and substrate) and temperature with range	US-PGPUB	2004/07/06 16:30
11	434	(((heat$3 same die) and substrate) and temperature with range) and epoxy	US-PGPUB	2004/07/06 16:31
13	0	(((((heat$3 same die) and substrate) and temperature with range) and epoxy) and nozzle) and 219/548	US-PGPUB	2004/07/06 16:33
14	2	(((((heat$3 same die) and substrate) and temperature with range) and epoxy) and nozzle) and 219/$	US-PGPUB	2004/07/06 16:35
12	88	((((heat$3 same die) and substrate) and temperature with range) and epoxy) and nozzle	US-PGPUB	2004/07/06 16:32
15	2	(((heat$3 same die) and substrate) and temperature with range) and 219/548	US-PGPUB	2004/07/06 16:34
16	2	((heat$3 same die) and substrate) and 219/548	US-PGPUB	2004/07/06 16:34
17	4	(heat$3 same die) and 219/548	US-PGPUB	2004/07/06 16:34
18	5	(heat$3 same die same nozzle) and 219/$	US-PGPUB	2004/07/06 16:35
19	7	(heat$3 same die same nozzle) and underfill	US-PGPUB	2004/07/06 16:38
20	4	heat$3 same die and 219/548	US-PGPUB	2004/07/06 16:41
21	7	((heat$3 same die same nozzle) and underfill) and substrate	US-PGPUB	2004/07/06 16:43
22	2339	heat$3 same die same nozzle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/06 16:43
23	80	(heat$3 same die same nozzle) and substrate	US-PGPUB	2004/07/06 16:44
24	368	(heat$3 same die same nozzle) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/06 16:45
25	116	((heat$3 same die same nozzle) and substrate) and epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/06 16:46
26	93	(((heat$3 same die same nozzle) and substrate) and epoxy) and temperature	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/06 16:46